



DFLS260

# 2.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER POWERDI® 123

#### **Features**

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- Qualified to AEC-Q101 Standards for High Reliability
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Green Molding Compound (No Br, Sb)
  - Halogen and Antimony Free. "Green" Device (Note 3)

### **Mechanical Data**

- Case: PowerDI<sup>®</sup>123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202 Method 208 (23)
- Weight: 0.01 grams (approximate)

PowerDI®123



Top View

### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DFLS260-7	PowerDI <sup>®</sup> 123	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## Marking Information



F17A = Product Type Marking Code YM = Date Code Marking Y = Year (ex: V = 2008)

M = Month (ex: 9 = September)

Date Code Kev

Year	2008		2009	2010		2011	2012		2013	2014		2015
Code	V		W	Х		Υ	Z		Α	В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## 

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>R</sub> WM V <sub>R</sub>	60	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	42	V
Average Forward Current	I <sub>F(AV)</sub>	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	50	А

### **Thermal Characteristics**

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance Junction to Soldering Point (Note 6)	$R_{\theta JS}$	_	6	°C/W
Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	125	_	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to	+150	°C

## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	60		_	V	$I_R = 0.2 \text{mA}$
Forward Voltage	V <sub>F</sub>	_		0.62 0.56		I <sub>F</sub> = 2.0A, T <sub>A</sub> = +25°C I <sub>F</sub> = 2.0A, T <sub>A</sub> = +125°C
Leakage Current (Note 7)	I <sub>R</sub>	_	_	0.1	mA	$V_R = 60V, T_A = +25^{\circ}C$
Total Capacitance	C <sub>T</sub>	_	67	_	pF	$V_R = 10V, f = 1.0MHz$

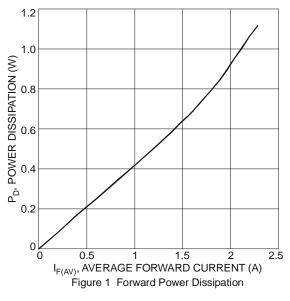
Notes:

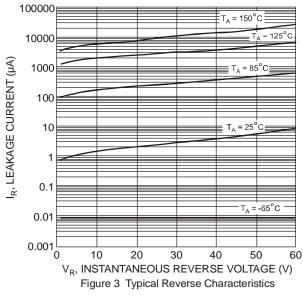
- 5. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

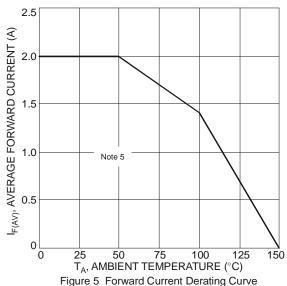
  6. Theoretical R <sub>JS</sub> calculated from the top center of the die straight down to the PCB/cathode tab solder junction.

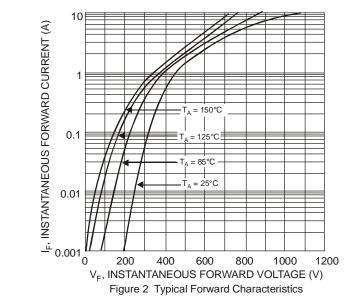
  7. Short duration pulse test to minimize self-heating effect.











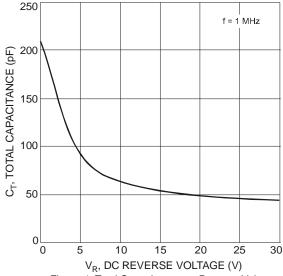
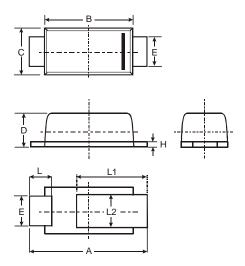


Figure 4 Total Capacitance vs. Reverse Voltage

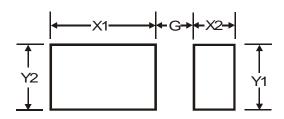


## **Package Outline Dimensions**



	PowerDI <sup>®</sup> 123						
Dim	Min	Max	Тур				
Α	3.50	3.90	3.70				
В	2.60	3.00	2.80				
С	1.63	1.93	1.78				
D	0.93	1.00	0.98				
Е	0.85	1.25	1.00				
Н	0.15	0.25	0.20				
L	0.55	0.75	0.65				
L1	1.80	2.20	2.00				
L2	0.95	1.25	1.10				
All D	All Dimensions in mm						

## **Suggested Pad Layout**



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4



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